

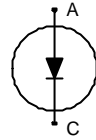
## Diode EMCON 4 High Power Chip

### FEATURES:

- 1200V EMCON 4 technology
- soft, fast switching
- low reverse recovery charge
- small temperature coefficient

### This chip is used for:

- medium / high power modules



### Applications:

- medium / high power drives

Chip Type	V <sub>R</sub>	I <sub>F</sub>	Die Size	Package
IDC73D120T6H	1200V	150A	8.15 x 9.00 mm <sup>2</sup>	sawn on foil

### MECHANICAL PARAMETER:

Raster size	8.15 x 9.00	mm <sup>2</sup>
Area total / active	73.35 / 59.89	
Anode pad size	7.196 x 8.046	
Thickness	120	µm
Wafer size	150	mm
Flat position	180	deg
Max. possible chips per wafer	187 pcs	
Passivation frontside	Photoimide	
Pad metall	3200 nm AlSiCu	
Backside metall	Ni Ag –system suitable for epoxy and soft solder die bonding	
Die bond	electrically conductive glue or solder	
Wire bond	Al, ≤500µm	
Reject ink dot size	Ø 0.65mm; max 1.2mm	
Recommended storage environment	store in original container, in dry nitrogen, < 6 month at an ambient temperature of 23°C	

## Maximum Ratings

Parameter	Symbol	Condition	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$		1200	V
Continuous forward current limited by $T_{jmax}$	$I_F$		1)	A
Maximum repetitive forward current limited by $T_{jmax}$	$I_{FRM}$		300	
Maximum junction and storage temperature	$T_{vj,max}$ , $T_{stg}$		-40...+175	°C
Reverse bias safe operating area <sup>2)</sup> (RBSOA)	$I_{F,max} = 300A$ , $V_{R,max} = 1200V$ , $T_{vj,op} \leq 150^\circ C$ , $P_{max} = \mathbf{tbd}$ kW			

1) depending on thermal properties of assembly

2) not subject to production test - verified by design/characterisation

## Static Electrical Characteristics (tested on wafer), $T_j=25^\circ C$

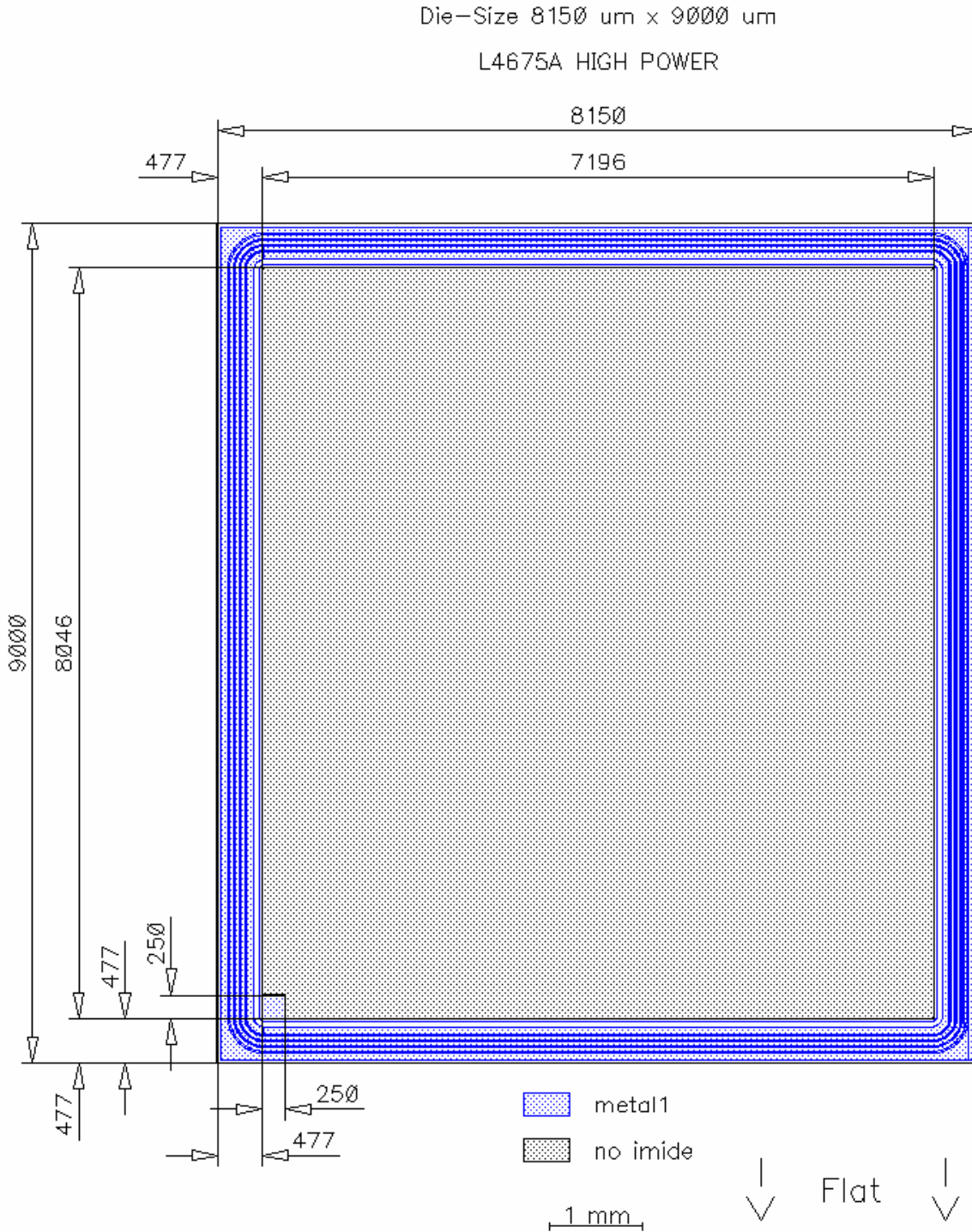
Parameter	Symbol	Conditions		Value			Unit
				min.	Typ.	max.	
Reverse leakage current	$I_R$	$V_R=1200V$	$T_j=25^\circ C$			26	$\mu A$
Cathode-Anode breakdown Voltage	$V_{Br}$	$I_R=0.25mA$	$T_j=25^\circ C$	1200			V
Forward voltage drop	$V_F$	$I_F=150A$	$T_j=25^\circ C$	1.55	1.9	2.25	V

## Dynamic Electrical Characteristics inductive load (not subject to production test - verified by design/characterization)

Parameter	Symbol	Conditions		Value <sup>2)</sup>			Unit
				min.	Typ.	max.	
Peak reverse recovery current	$I_{RM}$	$I_F=A$ $di/dt=A/ms$ $V_R=V$ $V_{GE}=-15V$	$T_j = 25^\circ C$ $T_j = 125^\circ C$ $T_j = 150^\circ C$		tbd		A
Reverse recovery charge	$Q_r$	$I_F=A$ $di/dt=A/ms$ $V_R=V$ $V_{GE}=-15V$	$T_j = 25^\circ C$ $T_j = 125^\circ C$ $T_j = 150^\circ C$		tbd		$\mu C$
Reverse recovery energy	$E_{rec}$	$I_F=A$ $di/dt=A/ms$ $V_R=V$ $V_{GE}=-15V$	$T_j = 25^\circ C$ $T_j = 125^\circ C$ $T_j = 150^\circ C$		tbd		mJ

2) values also influenced by parasitic L- and C- in measurement and package.

**CHIP DRAWING:**





# IDC73D120T6H

## FURTHER ELECTRICAL CHARACTERISTICS:

This chip data sheet refers to the device data sheet

tbd

## Description:

AQL 0,65 for visual inspection according to failure catalog

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Test-Normen Villach/Prüffeld

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